Build Up HDI (Standard)

HDI06_2+2+2_0,80_35_engl

6 - Layers

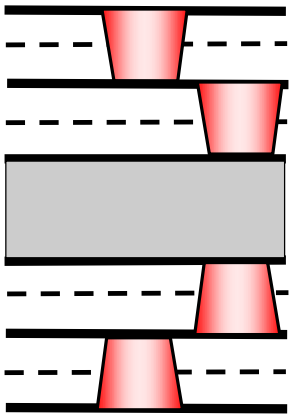
Core: 0,41 mm Cu 35/35 µm

WE-Articel No.:

2 + 2 + 2

Customer:

WÜRTH ELEKTRONIK

layer description		configuration	Raw-Material	CU	PREPREG	Final Thickness	Customer requirements
Customer	WE					[µm]	[µm]
	TOP/VS		Foil	12 µm	1)	12	
					1 x 1080	**60**	
	2		Foil	12 µm		**30**	
					1 x 1080	**60**	
	3			35 µm		**33**	
			0,410 mm			**410**	
	4			35 µm		**33**	
					1 x 1080	**60**	
	5		Foil	12 µm		**30**	
					1 x 1080	**60**	
	BOT/RS		Foil	12 µm	1)	12	

1) copper thickness outer layers: appr. 55 µm

total material thickness: 800

Note: Lamination thickness for Prepregs depending on layout characteristics.

final lamination thickness:	**0,80**	+/-	0,07	mm			Date: / Engineer:
thickness with electro plated Cu:	0,89	+/-	0,10	mm			
total thickness with soldermask	0,95	+/-	0,12	mm			
customer requirement		+/-		mm	point:		

prepared: on	by	checked: on	by	approved: on	by	revision	
05.01.2006	**S. Keller**	04.05.2006	M.Kress	05.01.2006	R. Schönholz	00	page: 12+